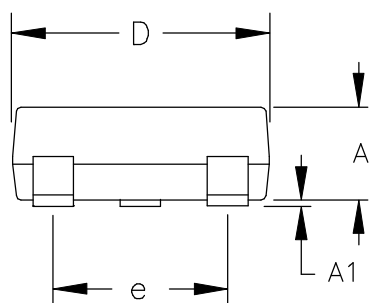
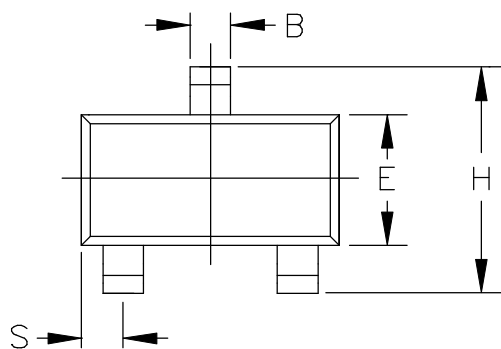


	INCHES	
LTR	MIN	MAX
A	0.030	0.040
A1	0.001	0.006
B	0.015	0.022
C	0.003	0.008
D	0.100	0.120
E	0.040	0.060
e	0.070	0.085
H	0.080	0.100
I	0.005	0.015
S	0.015	0.025
θ	0°	8°

NOTES:

1. PACKAGE OUTLINE EXCLUSIVE OF ANY MOLD FLASHES DIMENSION.
2. PACKAGE OUTLINE EXCLUSIVE OF BURR DIMENSION.

SIGNATURE		DATE	 Dallas Semiconductor		
DOC. CONTROL:					
ENGR. MGR:					
MFG. ENGR:					
CHECKED BY:			TITLE		
DRAWN BY:			MARKETING OUTLINE, 3 LEAD, SOT-23 PACKAGE		
		SIZE	FSCM NO	PART NO.	REV
		A			A
DO NOT SCALE DWG.		SCALE N/A		SHEET 1 OF 1	